

PATENT APPLICATION

DECLARATION AND POWER OF ATTORNEY
FOR PATENT APPLICATION

ATTORNEY DOCKET NO. TSM03-0150

As a below named inventor, I hereby declare that my residence/post office address and citizenship are as stated below next to my name; That I verily believe that I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled as set forth below, which is described in the attached specification; that I have reviewed and understand the contents of the specification, including the claims, as amended by any amendment(s) referred to in the oath or declaration; that no application for patent or inventor's certificate on this invention has been filed by me or my legal representatives or assigns in any country foreign to the United States of America; and that I acknowledge my duty to disclose information which is material to the patentability of this application in accordance with Title 37 CFR 1.56.

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

Title of Invention:

Apparatus and Method for Manufacturing a Semiconductor Wafer with Reduced Delamination and Peeling

Power of Attorney: I hereby appoint the following attorney(s) and/or agent(s) listed below to prosecute this application and transact all business in the Patent and Trademark Office connected therewith.

Practitioners at Customer Number 25962

Send Correspondence to:

Direct Telephone Calls To:

Steven H. Slater
Slater & Matsil, L.L.P.
17950 Preston Rd.
Suite 1000
Dallas, Texas 75252-5793

Steven H. Slater
972-732-1001

Name of Inventor (1) Chao-Yuan Su	Name of Inventor (2) Pei-Haw Tsao	Name of Inventor (3) Hsin-Hui Lee
Residence (City and State Only) Koahsiung City	Residence (City and State Only) Tai-chung, Taiwan	Residence (City and State Only) Koahsiung City
Post Office Address: 6F, NO.383, Da-Shun 2nd Road San-Ming District	Post Office Address: No.1. 7 FL, Nan-Ho 2nd street, Nan-Ho	Post Office Address: 13F, No. 343, Fu-Ming Rd.
Country of Citizenship: Taiwan, R.O.C	Country of Citizenship: Taiwan, R.O.C.	Country of Citizenship: Taiwan, R.O.C
Signature of Inventor: Chao-Yuan Su	Signature of Inventor: Pei-Haw Tsao	Signature of Inventor: Hsin-Hui Lee
Date: 9/30/03'	Date: 9/30/03'	Date: 9/30/03'

Name of Inventor (4) Chender Huang	Name of Inventor (5) Shang Y Hou	Name of Inventor (6) Shin Puu Jeng
Residence (City and State Only) <i>Hsin-Chu, Taiwan</i>	Residence (City and State Only) <i>Hsinchu, TAIWAN</i>	Residence (City and State Only) <i>Hsinchu, TAIWAN</i>
Post Office Address: <i>6, Creation Rd, 2,</i>	Post Office Address: <i>8, Lane 29 Zi-Qiang S. Road, Chupei</i>	Post Office Address: <i>No. 10, Hu-Bing 1st Rd, Hsinchu, TAIWAN</i>
Country of Citizenship: <i>Taiwan</i>	Country of Citizenship: <i>Taiwan</i>	Country of Citizenship: <i>USA</i>
Signature of Inventor: <i>Chender Huang</i>	Signature of Inventor: <i>Shang Y Hou</i>	Signature of Inventor: <i>Shin Puu Jeng</i>
Date: <i>9/30/03</i>	Date: <i>9/29/2003</i>	Date: <i>9/29/2003</i>

Name of Inventor (7) Hao-Yi Tsai	Name of Inventor	Name of Inventor
Residence (City and State Only) <i>Hsinchu, TAIWAN</i>	Residence (City and State Only)	Residence (City and State Only)
Post Office Address: <i>5F-4, No. 98, Jianghong Rd. Hsinchu, Taiwan</i>	Post Office Address:	Post Office Address
Country of Citizenship: <i>Taiwan</i>	Country of Citizenship:	Country of Citizenship:
Signature of Inventor: <i>Hao Yi Tsai</i>	Signature of Inventor:	Signature of Inventor:
Date: <i>9/29/2003</i>	Date:	Date:

JAN 07 2004
PATENT & TRADEMARKS

Form PTO-1595
(Rev. 10/02)
OMB No. 0651-0027 (exp. 6/30/2005)

RECORDATION FORM COVER SHEET

U.S. DEPARTMENT OF COMMERCE
U.S. Patent and Trademark Office

PATENTS ONLY

To the honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):

Chao-Yuan Su Shang Y Hou
Pei-Haw Tsao Shin Pau Jeng
Hsin-Hui Lee
Chender Huang

Additional name(s) of conveying party(ies) attached? ☐ Yes ☒ No

3. Nature of conveyance:

☒ Assignment ☐ Merger
☐ Security Agreement ☐ Change of Name
☐ Other _____

Execution Date: Su, Tsao, Lee & Huang - 9/30/03;
Hou, Jeng & Tsai - 9/29/03

2. Name and address of receiving party(ies)

Name: Taiwan Semiconductor Manufacturing Company, Ltd.

Internal Address: _____

Street Address: No. 6, Li-Hsin Rd. 6

Science-Based Industrial Park

City: Hsin-Chu State: Taiwan Zip: 300-77

Additional name(s) & address(es) attached? ☐ Yes ☒ No

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is: _____

A. Patent Application No.(s) 10/675,862

B. Patent No.(s)

Additional numbers attached? ☐ Yes ☒ No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Steven H. Slater

Slater & Matsil, L.L.P.

Internal Address: _____

Street Address: 17950 Preston Rd.

Suite 1000

City: Dallas State: Texas Zip: 75252-5793

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41). \$ 40.00

☐ Enclosed

☒ Authorized to be charged to deposit account

8. Deposit account number:

50-1065

(Attach duplicate copy of this page if paying by deposit account)

DO NOT USE THIS SPACE

9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

James C. Kesterson
Name of Person Signing

James C. Kesterson
Signature

January 5, 2004
Date

Total number of pages including cover sheet, attachments, and documents: 3

Mail documents to be recorded with required cover sheet information to:
Commissioner of Patents & Trademarks, Mail Stop: Assignments
P. O. Box 1450, Alexandria, VA 22313-1450

ASSIGNMENT

WHEREAS, I, the undersigned inventor (or one of the undersigned joint inventors), of residence as listed, having invented certain new and useful improvements as below entitled, for which application for United States Letters Patent is made, the said application having been executed on the date set forth below; and

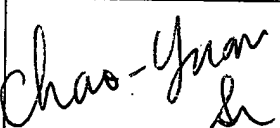
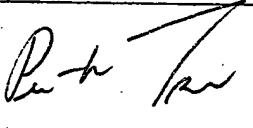
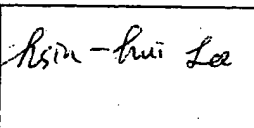
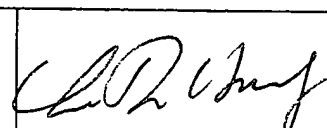
WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd. (TSMC), a corporation organized and existing under the laws of Taiwan, the Republic of China, with its principal office at No. 6, Li-Hsin Rd. 6, Science-Based Industrial Park, Hsin-Chu, Taiwan 300-77, R.O.C., is desirous of acquiring my entire right, title and interest in and to the said invention, and to the said application and any Letters Patent that may issue thereon in the United States and all other countries throughout the world;

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, I hereby sell and assign to the said TSMC, its successors and assigns, my entire right, title and interest in and to the said invention and in to the said application and all patents which may be granted therefor, and all divisions, reissues, substitutions, continuations, and extensions thereof; and I hereby authorize and request the Commissioner for Patents to issue all patents for said invention, or patent resulting therefrom, insofar as my interest is concerned, to the said TSMC, as assignee of my entire right, title and interest. I declare that I have not executed and will not execute any agreement in conflict herewith.

I also hereby sell and assign to TSMC, its successors and assigns, my foreign rights to the invention disclosed in said application, in all countries of the world, including, but not limited to, the right to file applications and obtain patents under the terms of the International Convention for the Protection of Industrial Property, and of the European Patent Convention, and further agree to execute any and all patent applications, assignments, affidavits, and any other papers in connection therewith necessary to perfect such patent rights.

I hereby further agree that I will communicate to said TSMC, or to its successors, assigns, and legal representatives, any facts known to me respecting said invention or the file history thereof, and at the expense of said assignee company, testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, reissue and substitute applications, make all lawful oaths, and generally do everything possible to aid said TSMC, its successors, assigns and nominees to obtain and enforce proper patent protection for said invention in all countries.

IN WITNESS WHEREOF, I hereunto set my hand and seal this day and year;

TITLE OF INVENTION	<i>Apparatus and Method for Manufacturing a Semiconductor Wafer with Reduced Delamination and Peeling</i>			
SIGNATURE OF INVENTOR AND NAME	 Chao-Yuan Su	 Pei-Haw Tsao	 Hsin-Hui Lee	 Chender Huang
DATE	9/30/03	9/30/03	9/30/03	9/30/03
RESIDENCE (City, County, State)	Hsin Chu Taiwan	Hsinchu, Taiwan	Hsin Chu, Taiwan	Hsin-Chu Taiwan

ATTORNEY DOCKET NO.
TSMC2003-0150

IN WITNESS WHEREOF, I hereunto set my hand and seal this day and year;

TITLE OF INVENTION	<i>Apparatus and Method for Manufacturing a Semiconductor Wafer with Reduced Delamination and Peeling</i>			
SIGNATURE OF INVENTOR AND NAME	<i>Shang Y Hou</i> Shang Y Hou	<i>SL-J</i> Shin Puu Jeng	<i>Hao Yi Tsai</i> Hao-Yi Tsai	
DATE	<i>Sept. 29, 2003</i>	<i>9.29, 2003</i>	<i>9.29. 2003</i>	
RESIDENCE (City, County, State)	<i>Hsinchu, TAIWAN</i>	<i>Hsinchu, TAIWAN</i>	<i>Hsinchu, TAIWAN</i>	